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MMBT2222A Taiwan Semiconductor

300mW, NPN Small Signal Transistor

FEATURES

TAIWAN

• Low power loss, high efficiency

MICONDUCTOR

- Ideal for automated placement
- High surge current capability
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter

MECHANICAL DATA

- Case: SOT-23
- Molding compound: UL flammability classification rating 94V-0
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 8 mg (approximately)

| KEY PARAMETERS | | | |
|------------------|-------------|------|--|
| PARAMETER | VALUE | UNIT | |
| V _{CBO} | 75 | V | |
| V _{CEO} | 40 | V | |
| V _{EBO} | 6 | V | |
| Ι _C | 600 | mA | |
| h _{FE} | 300 | | |
| Package | SOT-23 | | |
| Configuration | Single Dice | | |









| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | |
|---|------------------|-------------|------|--|--|
| PARAMETER | SYMBOL | MMBT2222A | UNIT | | |
| Marking code on the device | | 1P | | | |
| Collector-base voltage, emitter open | V _{CBO} | 75 | V | | |
| Collector-emitter voltage, base open | V _{CEO} | 40 | V | | |
| Emitter-base voltage, collector open | V _{EBO} | 6 | V | | |
| Collector current, dc | Ι _C | 600 | mA | | |
| Total dc power input to all terminals | P _T | 300 | mW | | |
| Junction temperature | TJ | -55 to +150 | °C | | |
| Storage temperature | T _{STG} | -55 to +150 | °C | | |



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| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | | |
|--|--|----------------------|-----|-----|------|------|
| PARAMETER | CONDITIONS | SYMBOL | MIN | ТҮР | MAX | UNIT |
| Collector-base breakdown voltage, emitter open | $I_{\rm C} = 10 \ \mu {\rm A}, \ I_{\rm E} = 0$ | V _{(BR)CBO} | 75 | - | - | v |
| Collector-emitter breakdown voltage, base open | $I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$ | V _{(BR)CEO} | 40 | - | - | V |
| Emitter-base breakdown voltage, collector open | $I_{E} = 10 \ \mu A, \ I_{C} = 0$ | V _{(BR)EBO} | 6 | - | - | V |
| Collector cutoff current, emitter open | $V_{CB} = 60 V, I_{E} = 0$ | I _{CBO} | - | - | 0.01 | μA |
| Emitter cutoff current, collector open | $V_{EB} = 3 V, I_C = 0$ | I _{EBO} | - | - | 0.1 | μA |
| | $V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$ | | 40 | - | - | |
| | $V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$ | | 100 | - | 300 | |
| DC Current Gain | $V_{CE} = 10 \text{ V}, I_{C} = 10 \text{ mA}$ | h _{FE} | 75 | - | - | |
| | $V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$ | | 50 | - | - | |
| | $V_{CE} = 10 \text{ V}, \text{ I}_{C} = 0.1 \text{ mA}$ | | 35 | - | - | |
| Collector-emitter saturation voltage | $I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}$ | V _{CE(sat)} | - | - | 1 | V |
| Base-emitter saturation voltage | $I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 50 \text{ mA}$ | $V_{BE(sat)}$ | - | - | 2 | V |
| Transition frequency | uency $V_{CE} = 20 \text{ V}$, $I_C = 20 \text{ mA}$, f= 100MHz | | 300 | - | - | MHz |
| Output Capacitance 1 MHz, $V_{CB} = 10 \text{ V}, I_E = 0$ | | C _{OBO} | 8 | | | pF |
| Input Capacitance | 1 MHz, V_{EB} = 0.5 V, I_C = 0 | CIBO | | 25 | | pF |
| Delay Time | V_{CC} =30V, $V_{BE(off)}$ = -0.5V, I _C =150mA | t _d | - | - | 10 | ns |
| Rise Time | I _{B1} =15mA | t _r | - | - | 25 | ns |
| Storage Time | V_{CC} =30V, I_{B1} = - I_{B2} =15mA, I_{C} =150mA | ts | - | - | 225 | ns |
| Fall Time | $V_{CC}=30V$, $I_{B1}=-I_{B2}=15mA$, $I_{C}=150mA$ | t _f | - | - | 60 | ns |



| ORDERING INFORMATION | | | | |
|-----------------------|-----------------|------------------------|---------|--------------|
| PART NO. | PACKING CODE | PACKING CODE SUFFIX | PACKAGE | PACKING |
| MMBT2222A (Note 1) | RF | G | SOT-23 | 3K / 7" Reel |

Notes:

1. Whole series with green compound

| EXAMPLE | | | | |
|---------------|-----------|--------------|------------------------|----------------|
| EXAMPLE P/N | PART NO. | PACKING CODE | PACKING CODE SUFFIX | DESCRIPTION |
| MMBT2222A RFG | MMBT2222A | RF | G | Green compound |



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)



Fig. 1Max Power Dissipation VS. Ambient Temperature



Fig.2 Typical Capacitance

Fig.3 Typical DC Current Gain VS. Collector Current



Fig.4 Gain Bandwidth Product VS. Collector Current





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)



Fig.5 Collector Emitter Saturation Voltage VS. Collector Current



Version:F1703



PACKAGE OUTLINE DIMENSION



| DIM | Unit(mm) | | Unit(inch) | |
|------|----------|------|------------|-------|
| DIW. | Min | Max | Min | Max |
| A | 2.70 | 3.10 | 0.106 | 0.122 |
| В | 1.10 | 1.50 | 0.043 | 0.059 |
| С | 0.30 | 0.51 | 0.012 | 0.020 |
| D | 1.78 | 2.04 | 0.070 | 0.080 |
| E | 2.10 | 2.64 | 0.083 | 0.104 |
| F | 0.89 | 1.30 | 0.035 | 0.051 |
| G | 0.55 REF | | 0.022 | REF |
| н | 0.10 REF | | 0.004 | REF |

SUGGEST PAD LAYOUT



| ЫМ | Unit(mm) | Unit(inch) |
|----|----------|------------|
| | ТҮР | ТҮР |
| Z | 2.8 | 0.11 |
| Х | 0.7 | 0.03 |
| Y | 0.9 | 0.04 |
| С | 1.9 | 0.07 |
| E | 1.0 | 0.04 |



Taiwan Semiconductor

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